

ABSTRACT OF THE DISCLOSURE

An electronic circuit module formed of an antenna coil and an integrated circuit provided on a circuit board is provided inside a hollow resin case formed of a first part and a second part. A first slit leading into the hollow portion is provided in one side face of the resin case formed of the first and second parts joined to each other. Since the electronic circuit module is not exposed to high temperatures and high pressure during the manufacturing process, defects such as the breakage of the integrated circuit or the disconnection of the antenna coil can be avoided. Since the slit leading into the hollow portion is provided, the hollow portion does not swell by the temperature increase. In addition, pinholes do not tend to be formed during the joining of the first and second parts. Thus, a contactless data carrier with an excellent electrostatic withstand voltage characteristic can be provided.